

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10043709	01/09/2002	25	878	2811	T.L.

**APPLICANTS: Chou Kuo-Yu; Lee Tze-Liang; Ong Tong-Chern;

**CONTINUING DATA VERIFIED: N

** FOREIGN APPLICATIONS VERIFIED: N

PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input checked="" type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners initials	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> yes <input checked="" type="checkbox"/> no	67,200-603

TITLE : Single layer wiring bond pad with optimum AL film thickness in Cu/FSG process for devices under 100s

U.S. DEPT. OF COMM /PAT & TM-PTO-435L(Rev. 12-94)

NOTICE OF ALLOWANCE MAILED

ISSUE FEE

Amount Due

Date Paid

TERMINAL

DISCLAIMER

Assistant Examiner

Primary Examiner

PREPARED FOR ISSUE

CLAIMS ALLOWED

Total Claims

Print Claim for
O.G.

DRAWING

Sheet(s) Drawn

Fig(s) Drawn

Print Fig.

Application Examiner

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CD-ROM

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